

## RELIABILITY MONITOR

### SAMPLING PLAN

DEVICE	REVISION	PROCESS	ASSEMBLY SITE	PINS	PACKAGE	WIDTH
DS1100	A3	06	ATP (Amkor, PI)	8	SOIC	150x1.4
DS1232	C2-L	08	ATP (Amkor, PI)	8	SOIC	150x1.4
DS1233	A5-500	12	Carsem	3	SOT223	140x1.7
DS1233	A5-500	12	Fastech	3	SOT223	140x1.7
DS1233	A5-500	12	Hana	3	SOT223	140x1.7
DS1267	A1	12	ATP (Amkor, PI)	20	TSSOP	4.4x0.9
DS12887	A2-C	06	Dallas	24	Module w/Bent Frame	720
DS12887	A2-C	06	Fastech	24	Module w/Bent Frame	720
DS1302	A4	08	ATP (Amkor, PI)	8	PDIP	300
DS1302	A4	08	CPS (ChipPac, China	8	PDIP	300
DS1620	D1	08	CPS (ChipPac, China	8	SOIC	208x1.9
DS1620	D1	08	NSEB	8	SOIC	208x1.9
DS1643	C1	06	Dallas	28	Module w/Hi Density SMT	720
DS1803	A2	08	ATP (Amkor, PI)	16	SOIC	150x1.4
DS1803	A2	08	OSEP	16	SOIC	150x1.4
DS1990	J3-F50-B	06	Fastech	2	iButton F50w/IC's	0
DS1992	E7-F50-E	08	Dallas	2	iButton F50 w/Bump	0
DS1992	E7-F50-E	08	Fastech	2	iButton F50 w/Bump	0
DS2108	B7	50	ATP (Amkor, PI)	24	SOIC	300x2.3
DS2118M	B1	06	Carsem	36	SSOP	7.5x2.4
DS2118M	C1	06	ATK (Amkor, K)	36	SSOP	7.5x2.4
DS21352	A4	06	ATP (Amkor, PI)	100	LQFP	14x14x
DS2154	A2	08	ATK (Amkor, K)	100	LQFP	14x14x

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DEVICE	REVISION	PROCESS	ASSEMBLY SITE	PINS	PACKAGE	WIDTH
DS2154	A2	08	ATP (Amkor, PI)	100	LQFP	14x14x
DS21Q43	A3-A	06	Stats	128	LQFP	14x20x
DS21S07	C1-A	08	Carsem	20	TSSOP	4.4x0.9
DS2401	C2	06	Carsem	3	SOT23	50x0.9
DS2401	C2	06	Fastech	3	TO92	150
DS2502	C4	06	OSEP	6	TSOC	150x1.2
DS29020	A7-340	06	Dallas	3	Cartridge	250
DS5002	C6	06	ATK (Amkor, K)	80	MQFP	14x20x
DS80CH11	A4	06	ATK (Amkor, K)	128	LQFP	14x20x
DS80CH11	A4	06	Stats	128	LQFP	14x20x
DS87C520	A15-I	06	ATP (Amkor, PI)	44	PLCC	650x65
DS87C520	A15-I	08	ATP (Amkor, PI)	44	PLCC	650x65